



FIG. 1

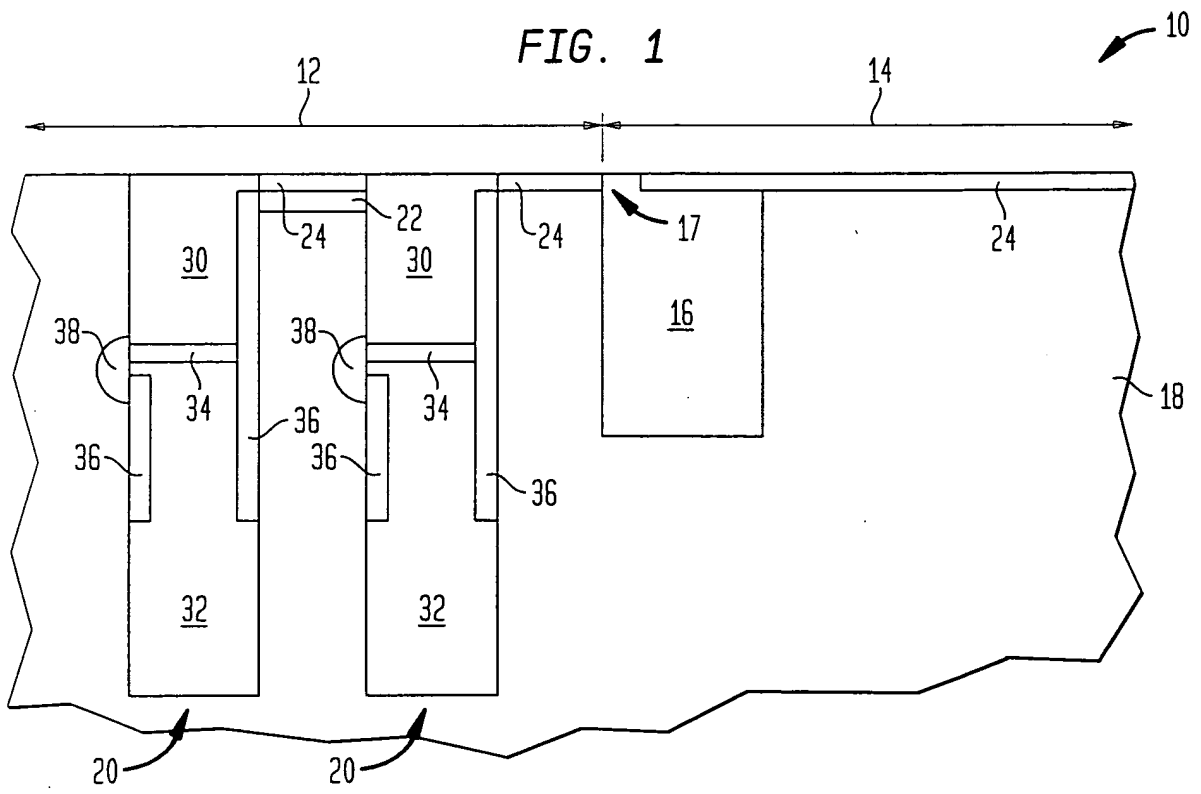
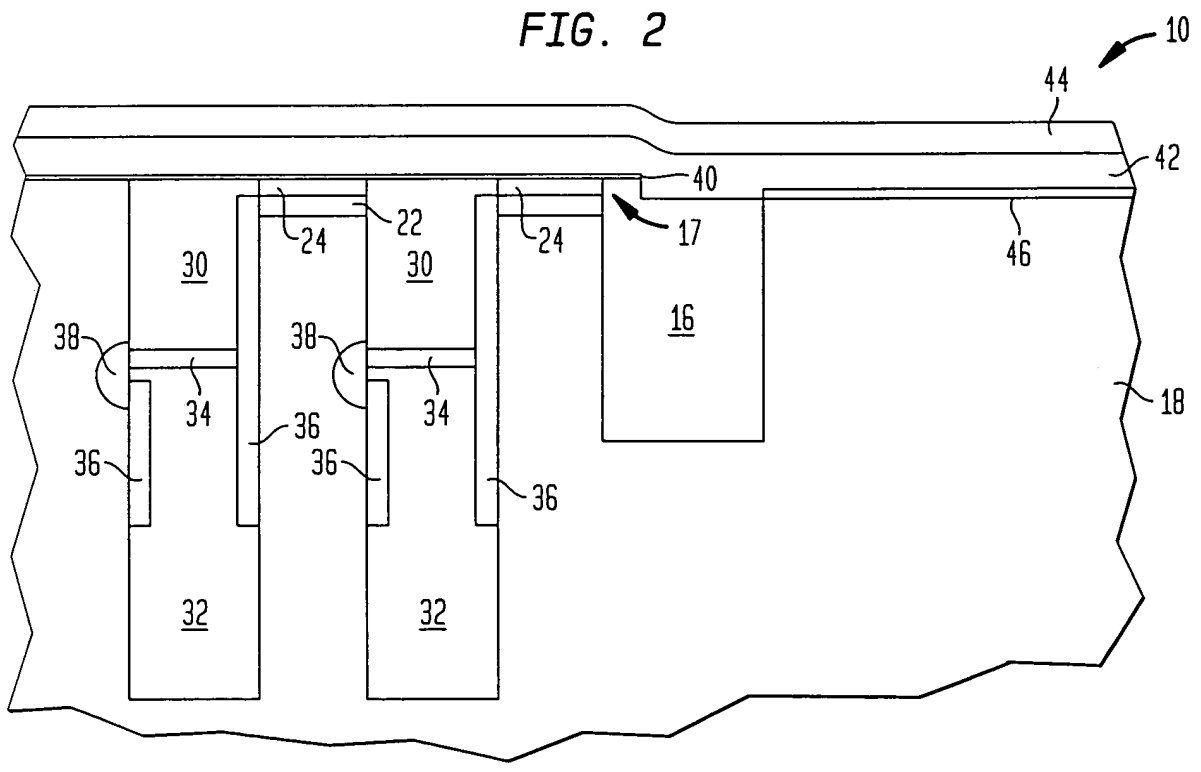
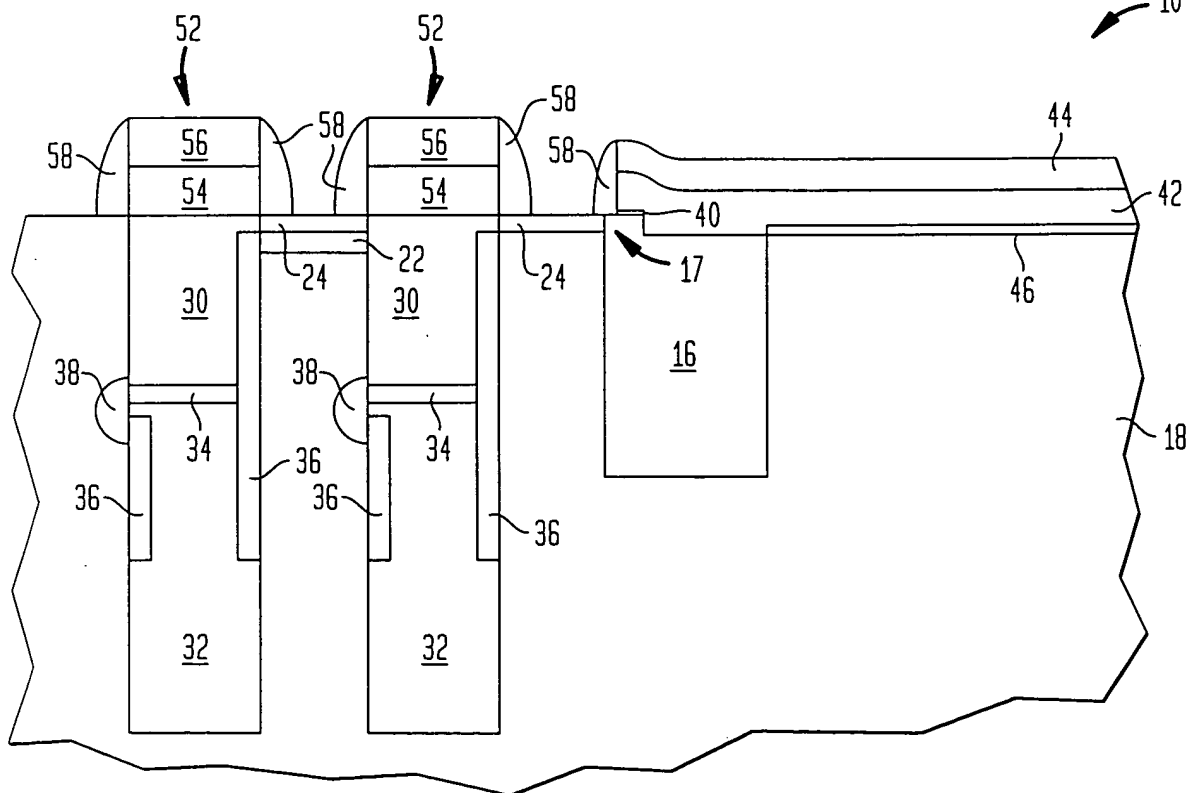
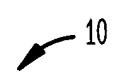
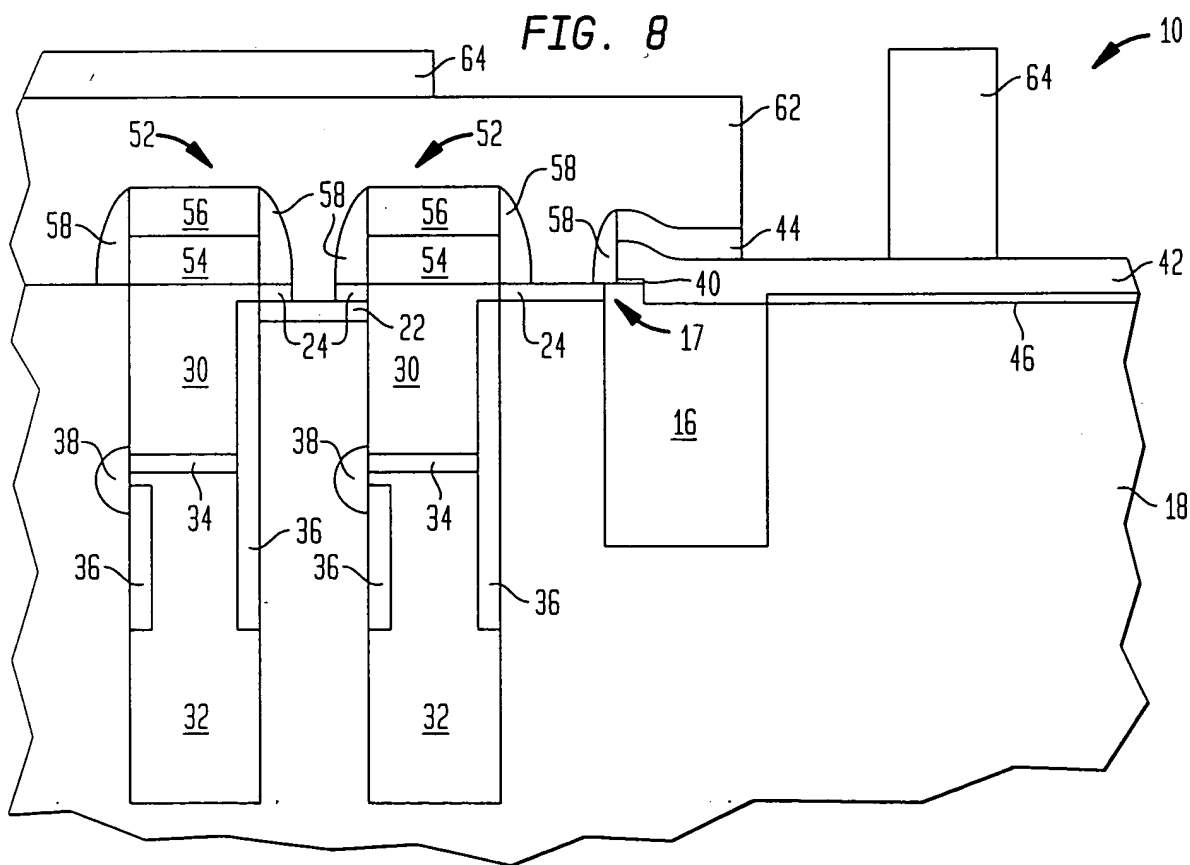


FIG. 2



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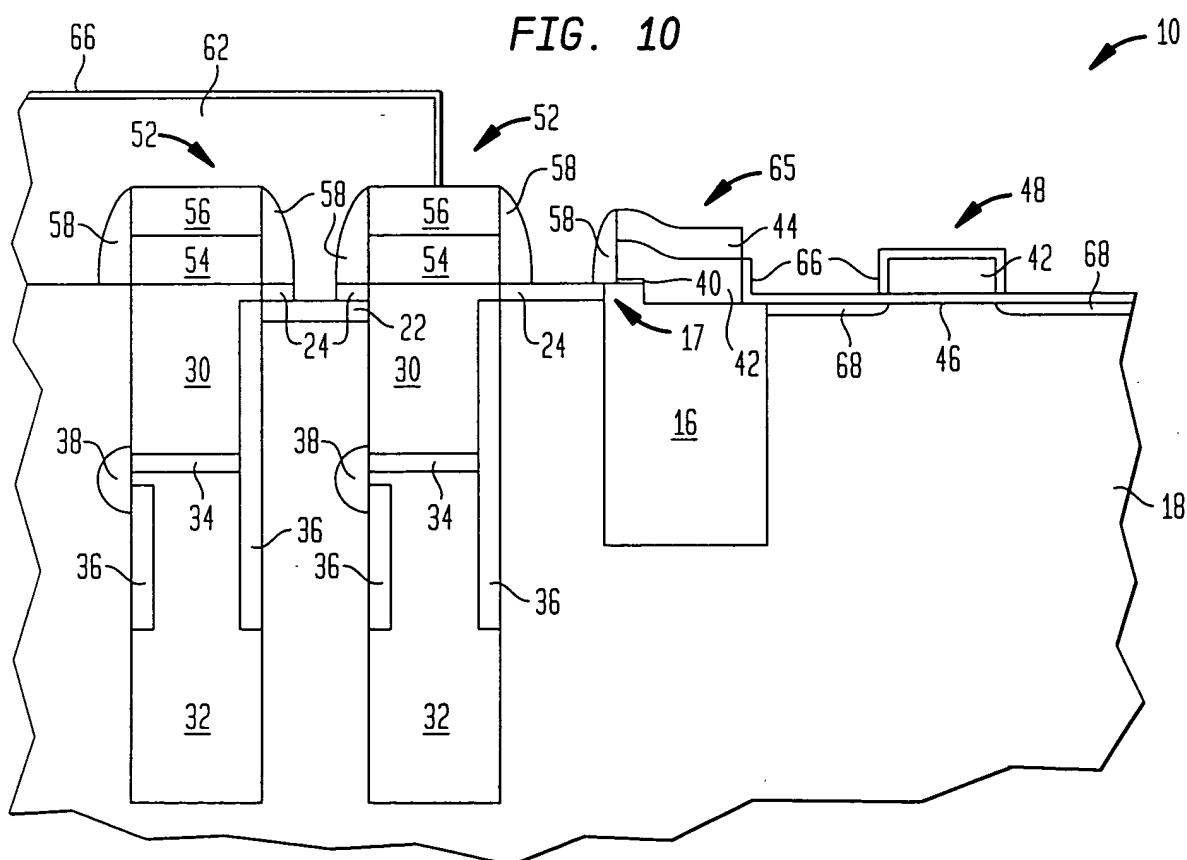


FIG. 11

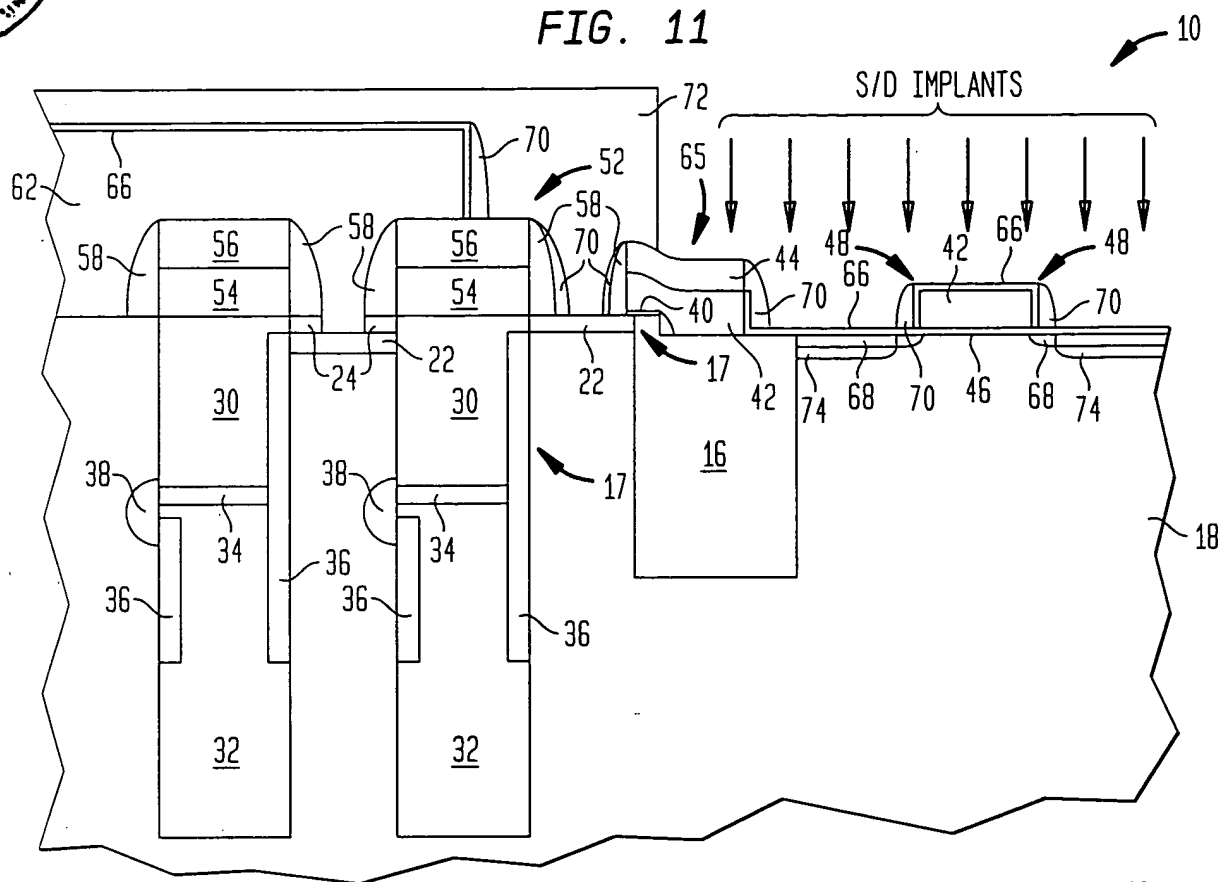


FIG. 12

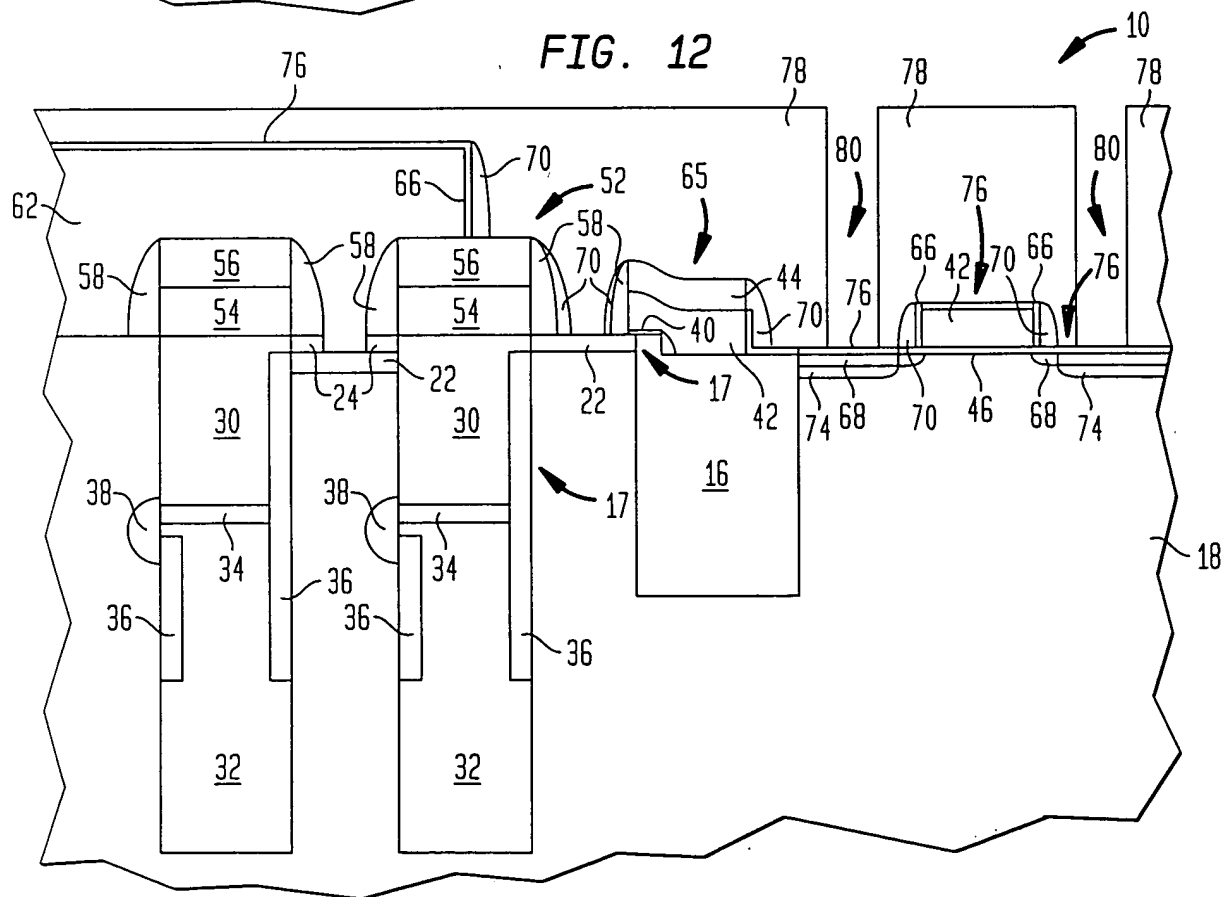




FIG. 13

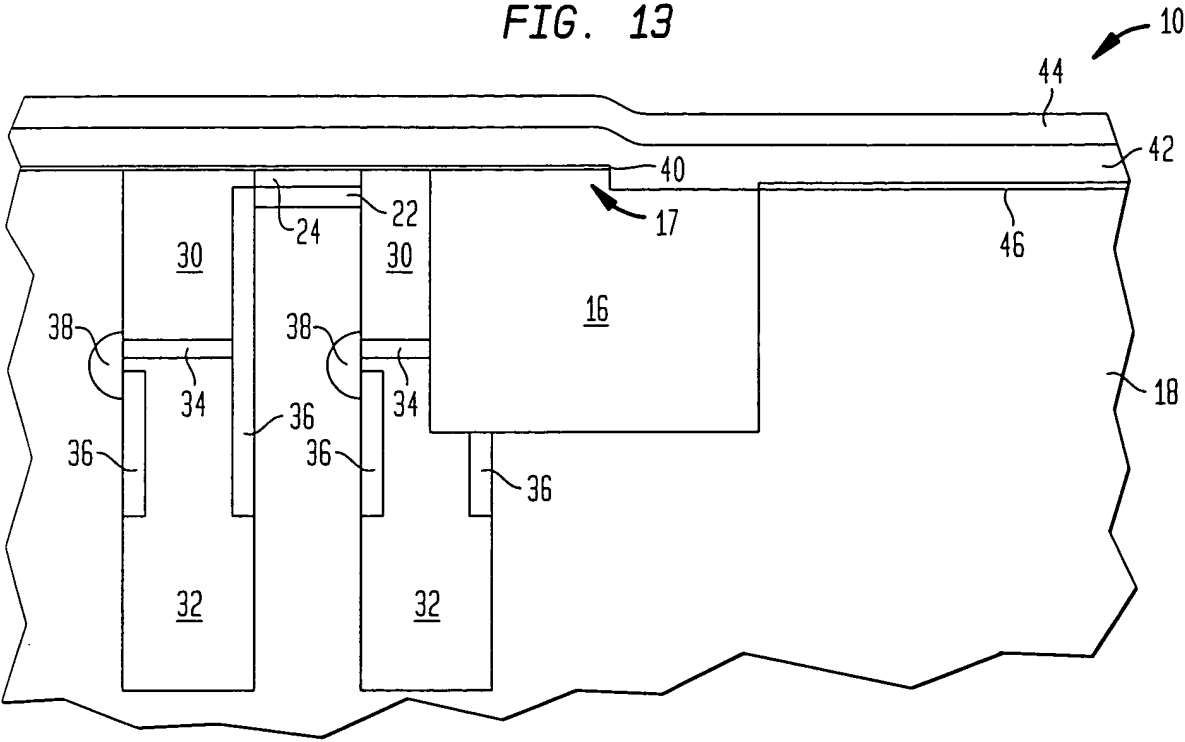


FIG. 14

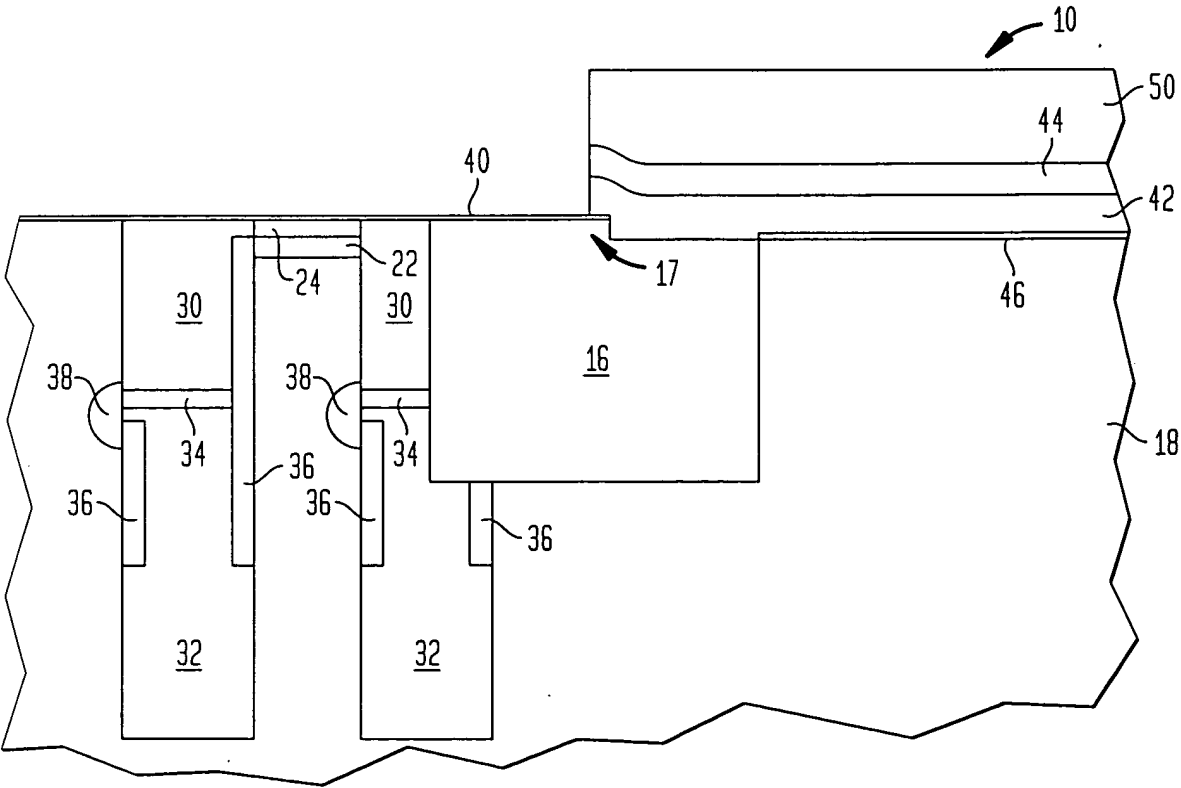


FIG. 10 is a cross-sectional view of a device assembly. The assembly includes a substrate 18 with a central cavity 16. On the left side of the cavity, there are two vertical structures 32. Each structure 32 has a base layer 36, a middle layer 34, and a top layer 38. A horizontal layer 24 is positioned between the two structures 32. Above each structure 32, there is a rectangular component 52. Component 52 consists of a lower part 54 and an upper part 56. A curved element 58 is shown connecting component 52 to the substrate 18. To the right of the cavity 16, there is a horizontal channel or passage 40. This channel leads to a larger opening 42 in the substrate 18. A layer 44 is located above the channel 40, and a layer 46 is located below it. An arrow 17 points towards the channel 40.



FIG. 17

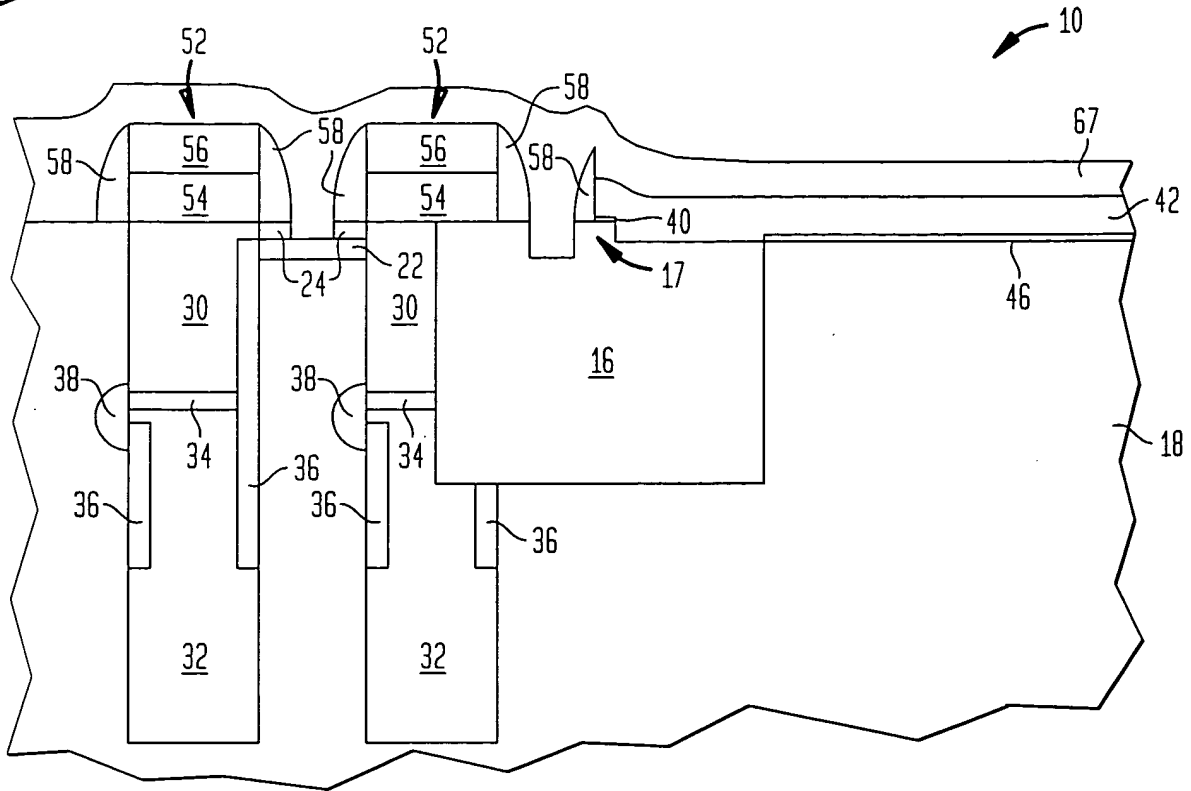
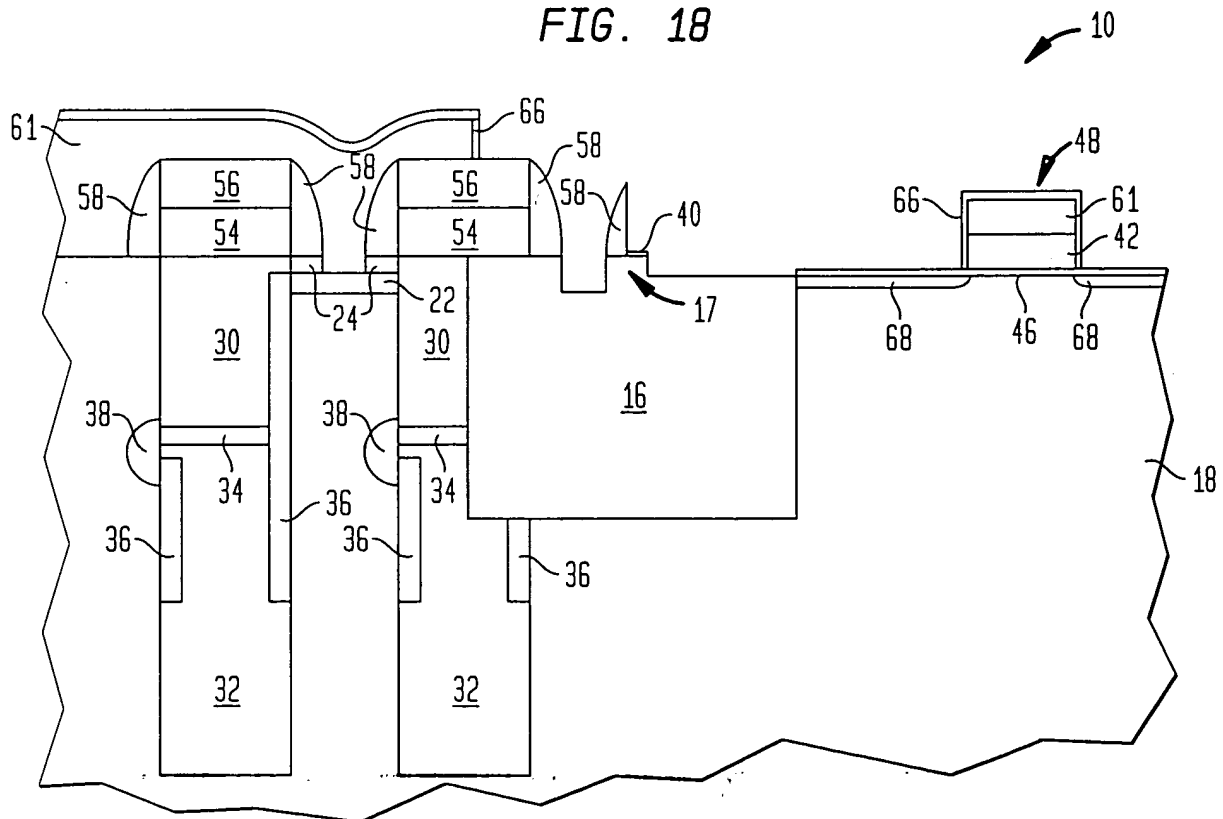


FIG. 18



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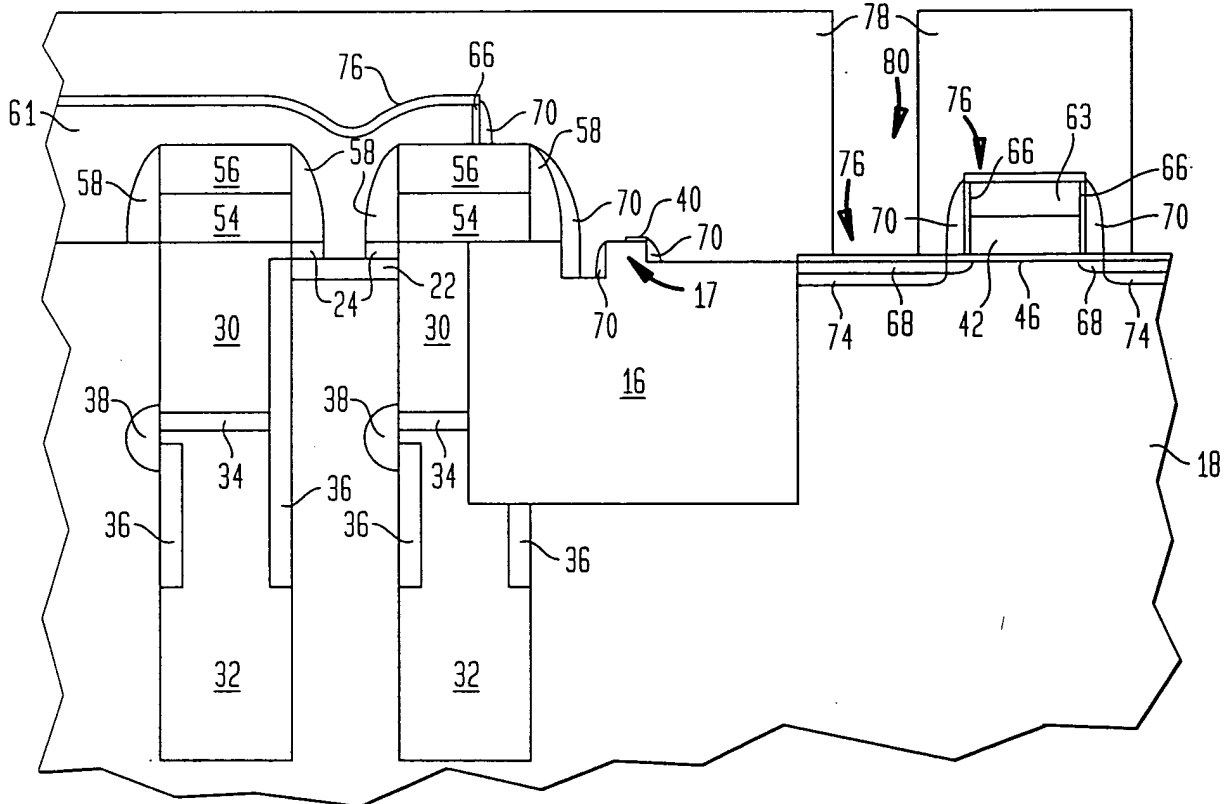


FIG. 21

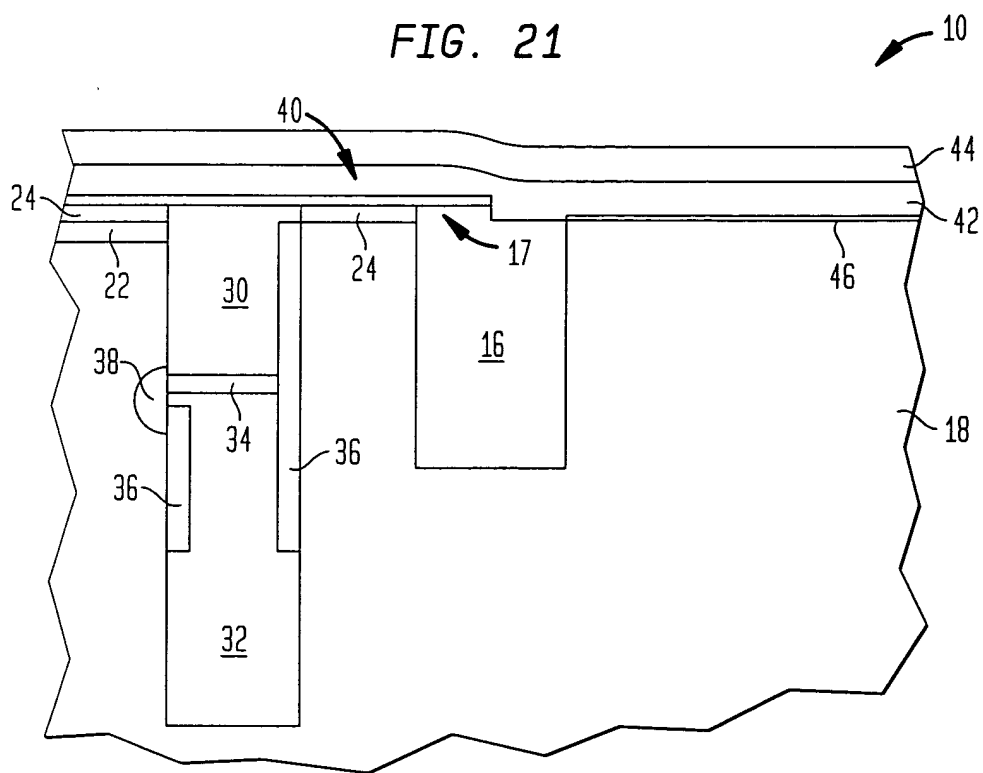
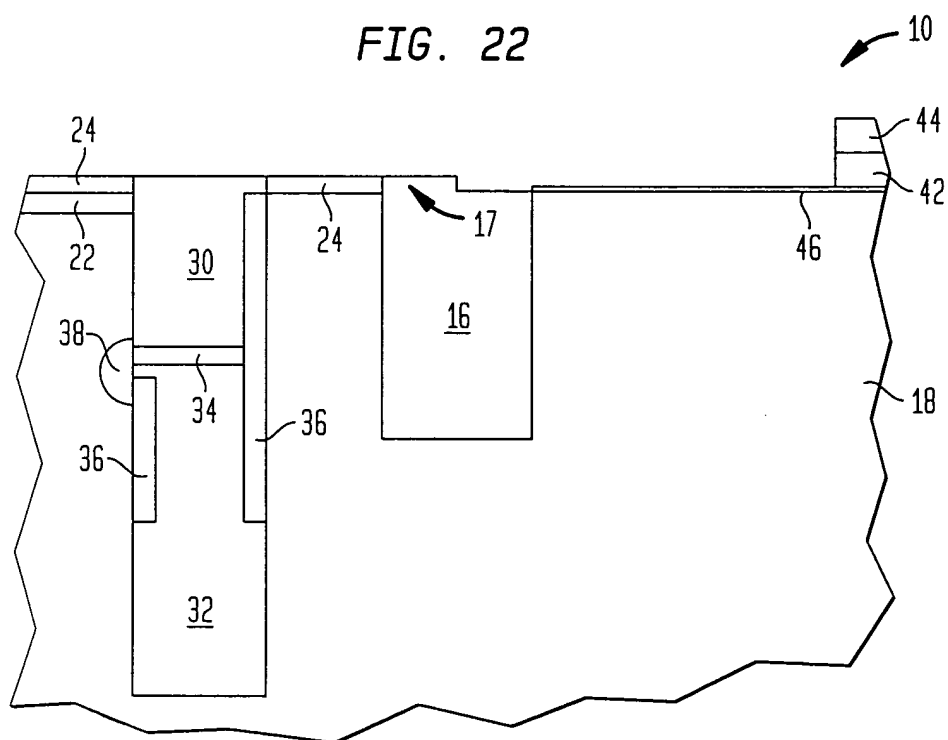


FIG. 22





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FIG. 23

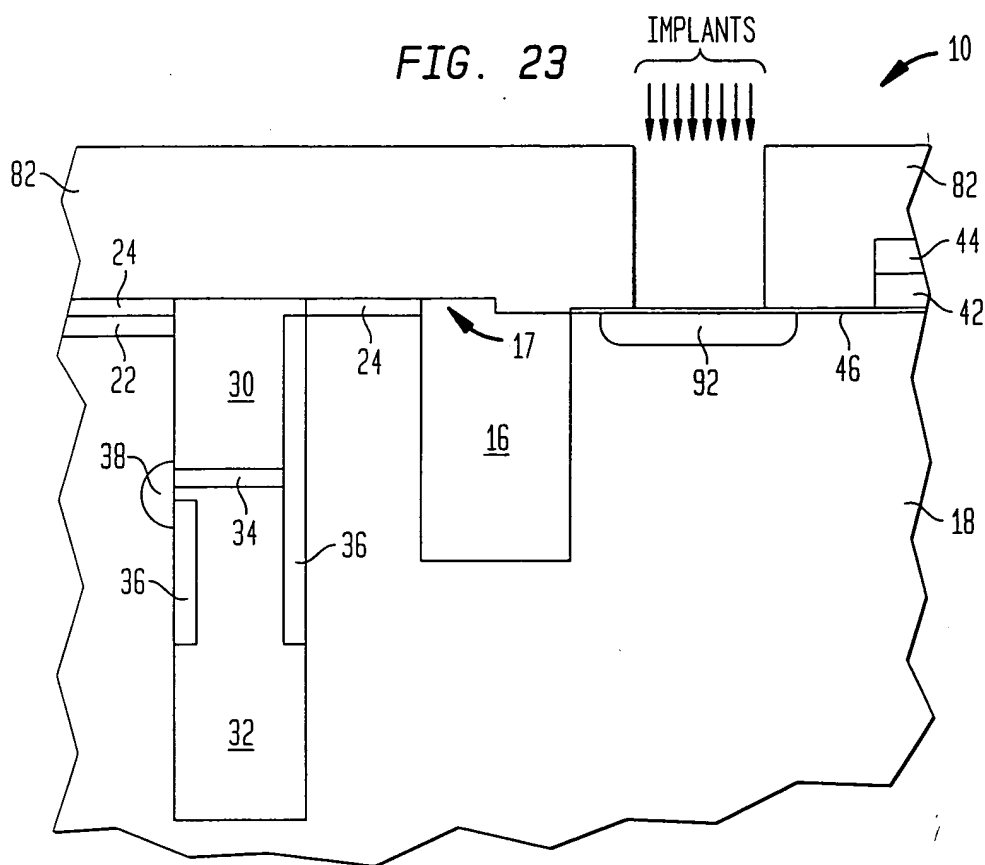
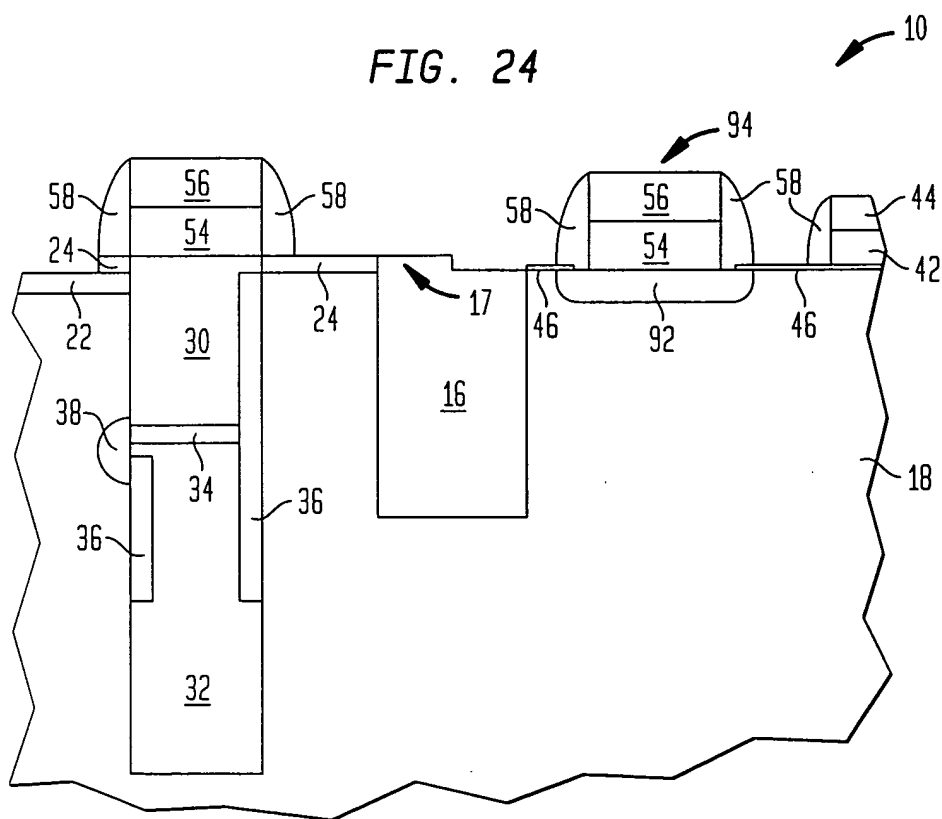


FIG. 24



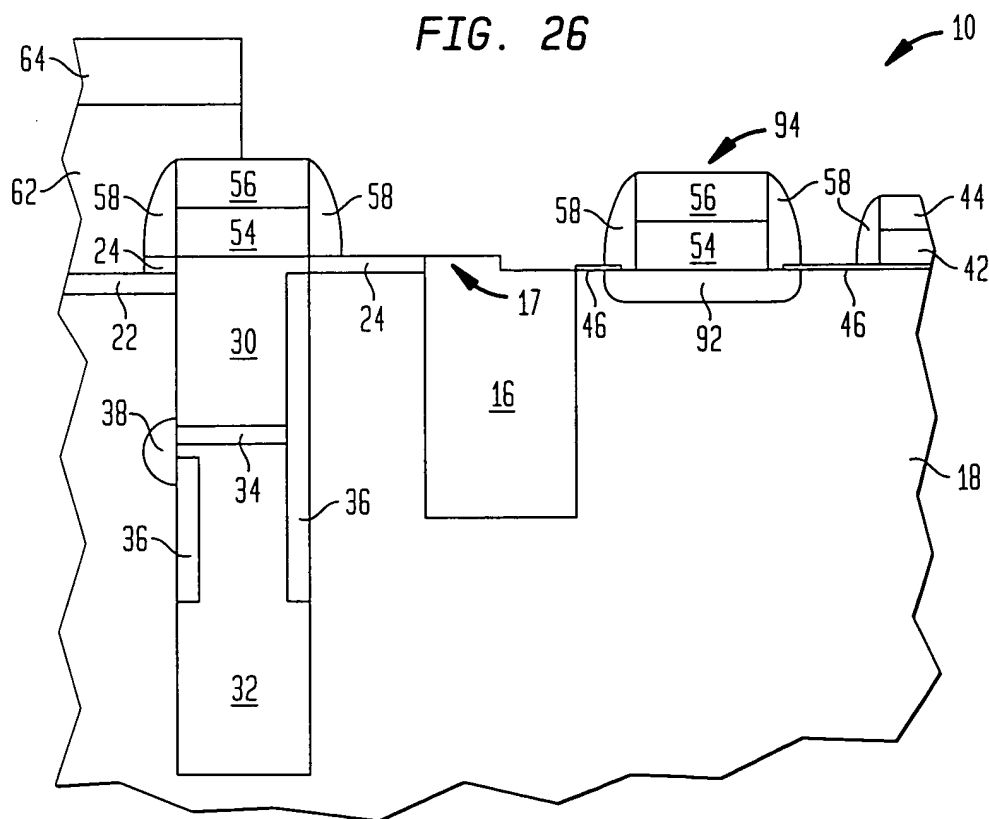




FIG. 27

